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(54) **Title:** DIE UP FULLY MOLDED FAN-OUT WAFER LEVEL PACKAGING

(57) **Abstract:** A method of manufacturing a semiconductor chip comprising placing a plurality of die units each having an active front surface and a back surface facing front surface up on an encapsulant layer, encapsulating the plurality of die units on the active surface of the encapsulant layer with an encapsulant covering a front surface and four side surfaces of each of the plurality of die units, and exposing, through the encapsulation on the front surface, conductive interconnects electrically connecting a die bond pad to redistribution layer.

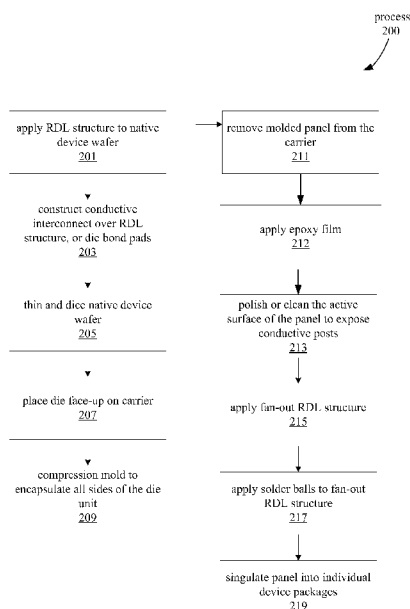


FIG. 2